

CARRIER HAVING LOCKING MECHANISM FOR HOLDING SUBSTRATES

ABSTRACT

An embodiment of the invention is a carrier apparatus for processing of a microelectronic device substrate and method of assembling a carrier apparatus. The carrier apparatus may include a first carrier plate for processing of a microelectronic device substrate, which includes a plurality of cantilevers formed therein. Each of the plurality of cantilevers may have a first end connected to the first carrier plate and a second end that is movable between a first configuration in which the second end is within a plane of the first carrier plate and a second configuration in which the second end is outside a plane of the first carrier plate. The apparatus may further include a second carrier plate for processing of a microelectronic device substrate, which includes a plurality of receiving slots formed therein.

Figure 4